

ABSTRACT

An epoxy resin composition comprising (A) an epoxy resin, (B) a phenol resin, (C) a curing accelerator, (D) silica, and (E) alumina and/or aluminum hydroxide, wherein the amount of aluminum to the total amount of the epoxy resin composition is 0.25-5 wt%, and 70 wt% or more of the silica has an average particle size of 25 μm or less. The epoxy resin composition for semiconductor encapsulating and a semiconductor device comprising a semiconductor element encapsulated using the composition possess excellent characteristics in reliability during high temperature operation.